



(51) International Patent Classification:
H01L 21/56 (2006.01) *H01L 23/31* (2006.01)

(21) International Application Number:
PCT/US2010/024462

(22) International Filing Date:
17 February 2010 (17.02.2010)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/388,092 18 February 2009 (18.02.2009) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,
NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD,
SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ,
TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— as to applicant's entitlement to apply for and be granted
a patent (Rule 4.17(ii))

Published:

— with international search report (Art. 21(3))

[Continued on next page]

(54) Title: SEMICONDUCTOR CHIP WITH REINFORCEMENT LAYER

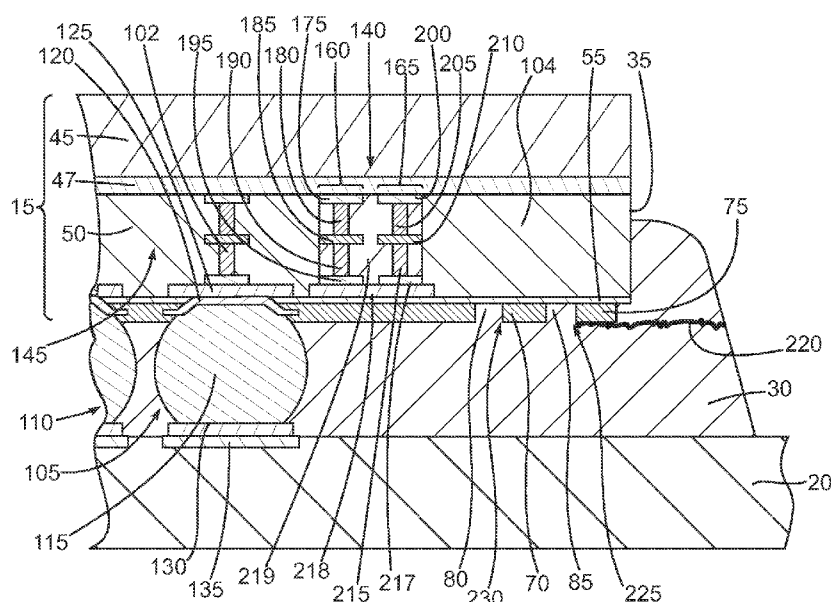


FIG. 4

(57) Abstract: Various semiconductor chip reinforcement structures and methods of making the same are disclosed. In one aspect, a method of manufacturing is provided that includes providing a semiconductor chip (15) that has a side (40) and forming a polymer layer (60) on the side (40). The polymer layer (60) has a central portion (65) and a first frame portion (70) spatially separated from the central portion (65) to define a first channel (80).



— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))*

(88) **Date of publication of the international search report:**
3 February 2011